
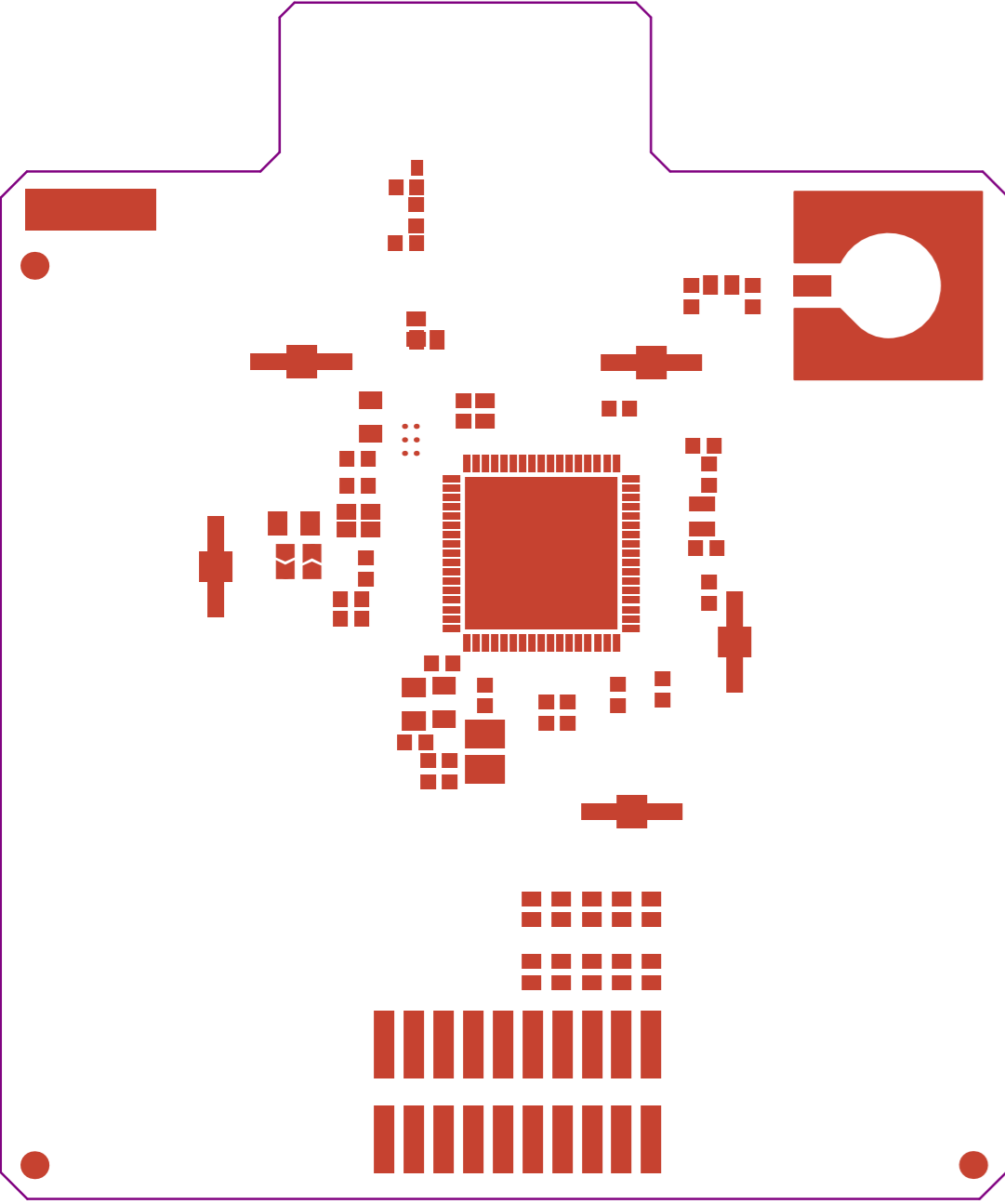

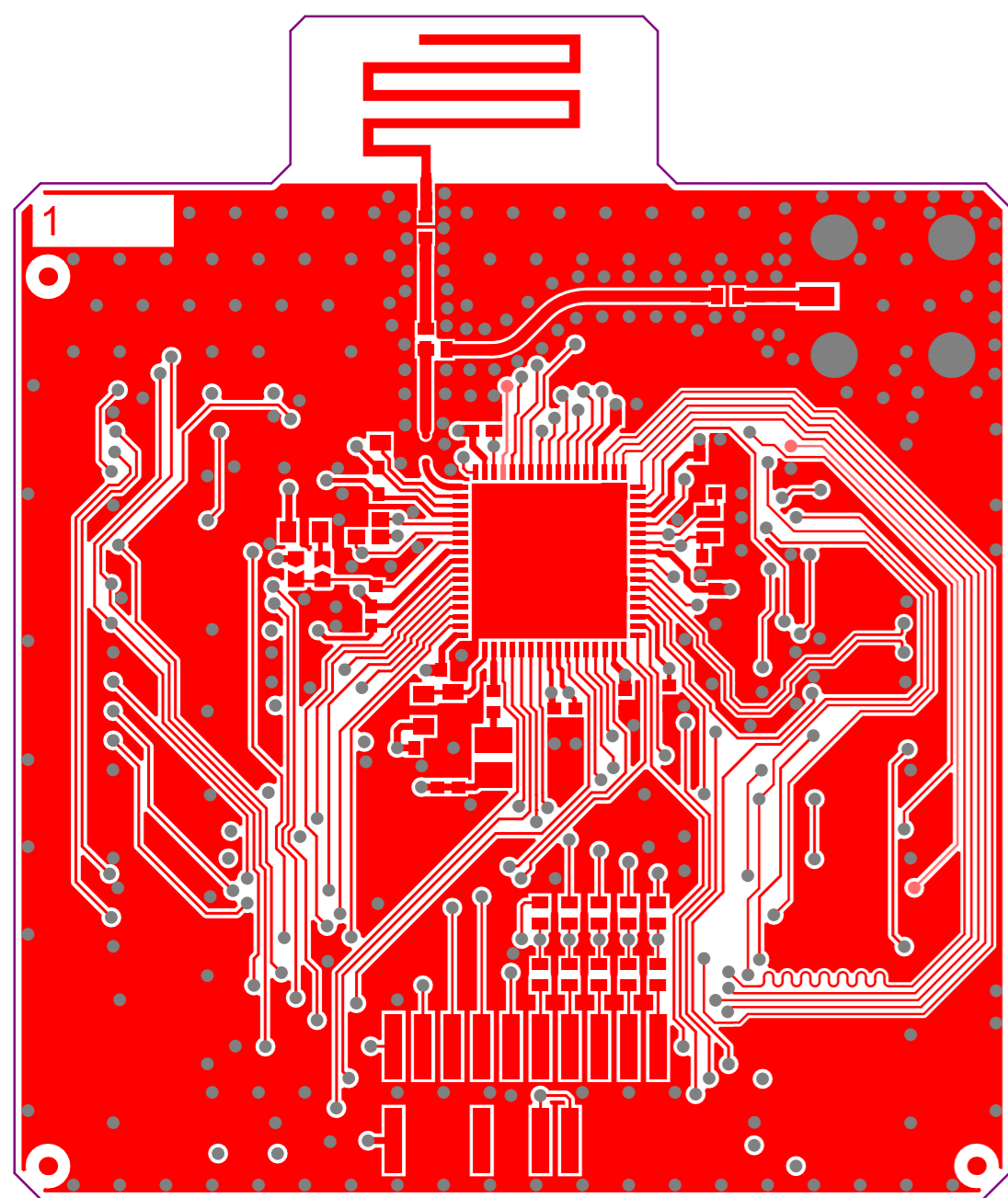



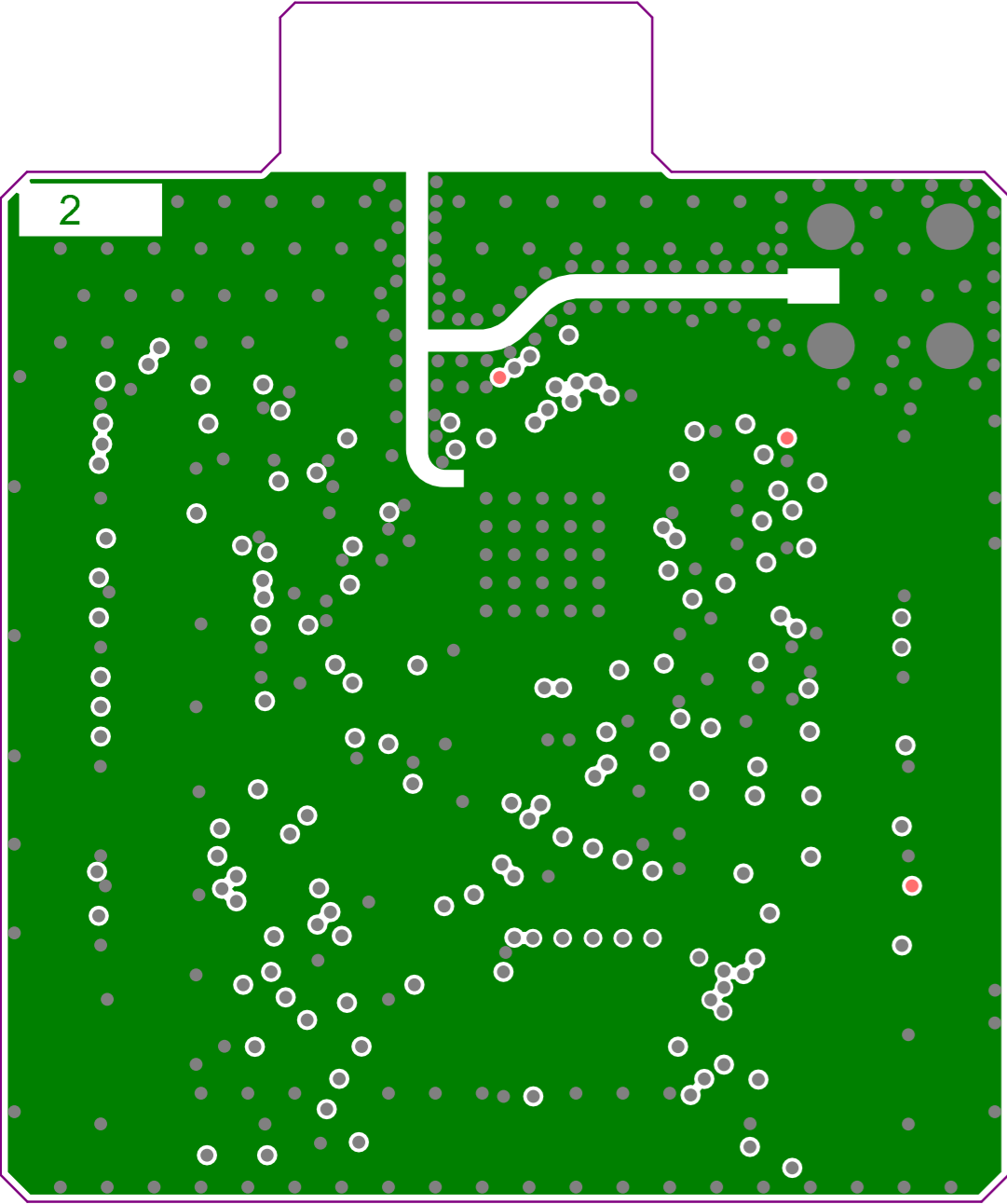
Project: MCU RF Board Bluefish 2M QFN68		
Layer: Top Overlay	Gerber: .GTO	
Variant: [No Variations]	Ref: MB2130	
Date: 23-FEB-24	Rev: A	




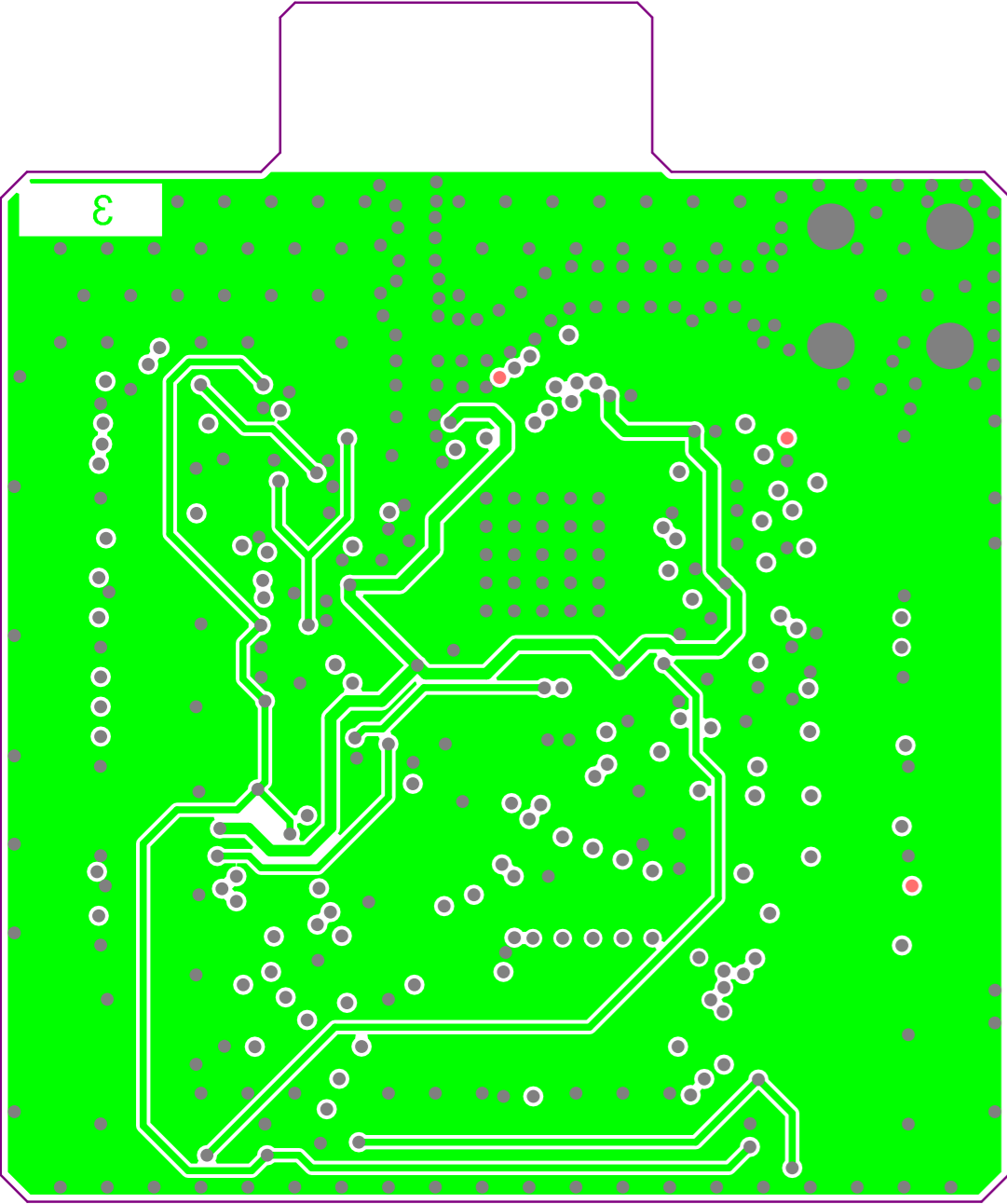
Project: MCU RF Board Bluefish 2M QFN68		
Layer: Top Solder	Gerber: .GTS	
Variant: [No Variations]	Ref: MB2130	
Date: 23-FEB-24	Rev: A	




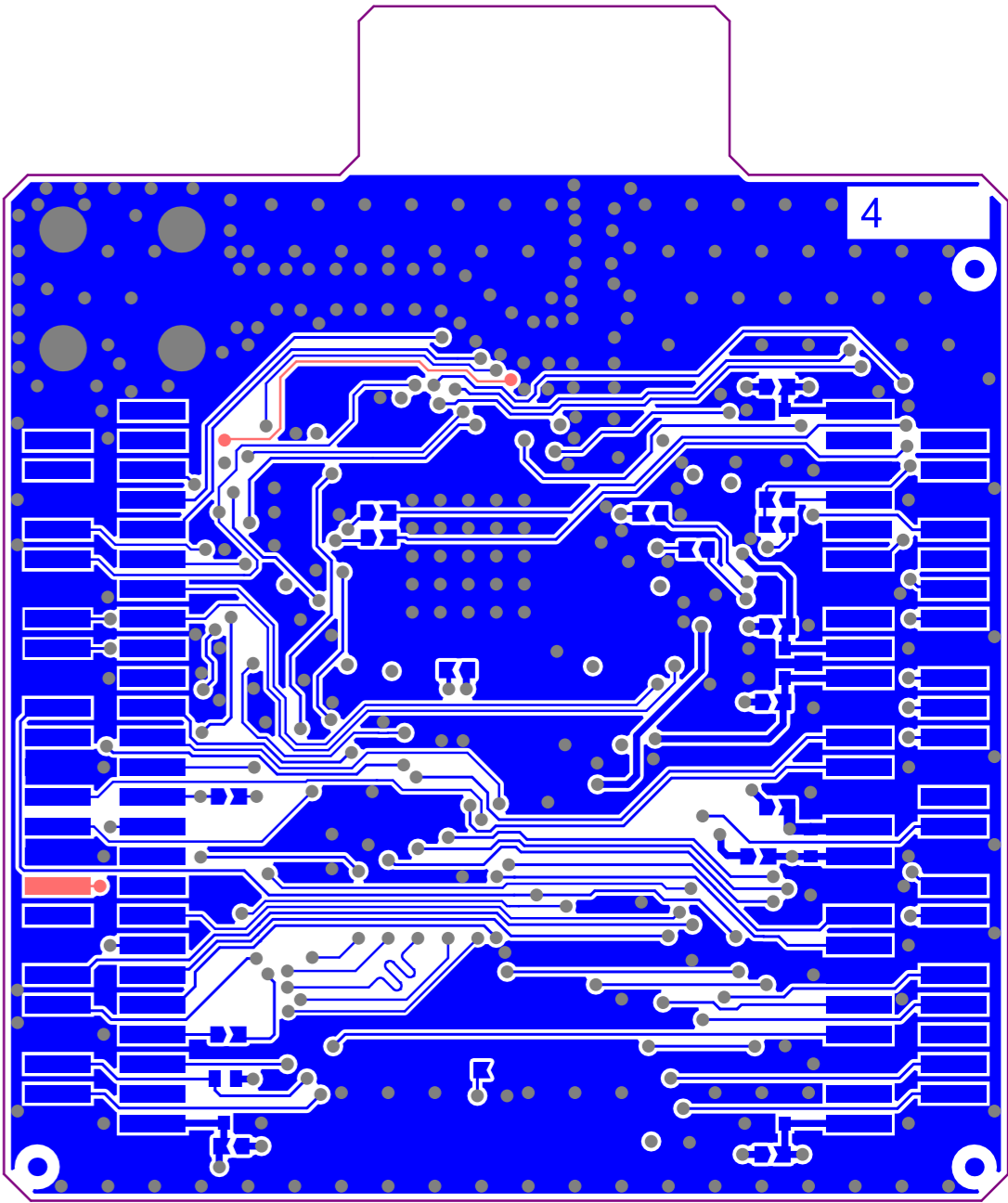
Project: MCU RF Board Bluefish 2M QFN68		
Layer: Top Layer	Gerber: .GTL	
Variant: [No Variations]	Ref: MB2130	
Date: 23-FEB-24	Rev: A	



Project: MCU RF Board Bluefish 2M QFN68		
Layer: Signal Layer 1	Gerber: .G1	
Variant: [No Variations]	Ref: MB2130	
Date: 23-FEB-24	Rev: A	

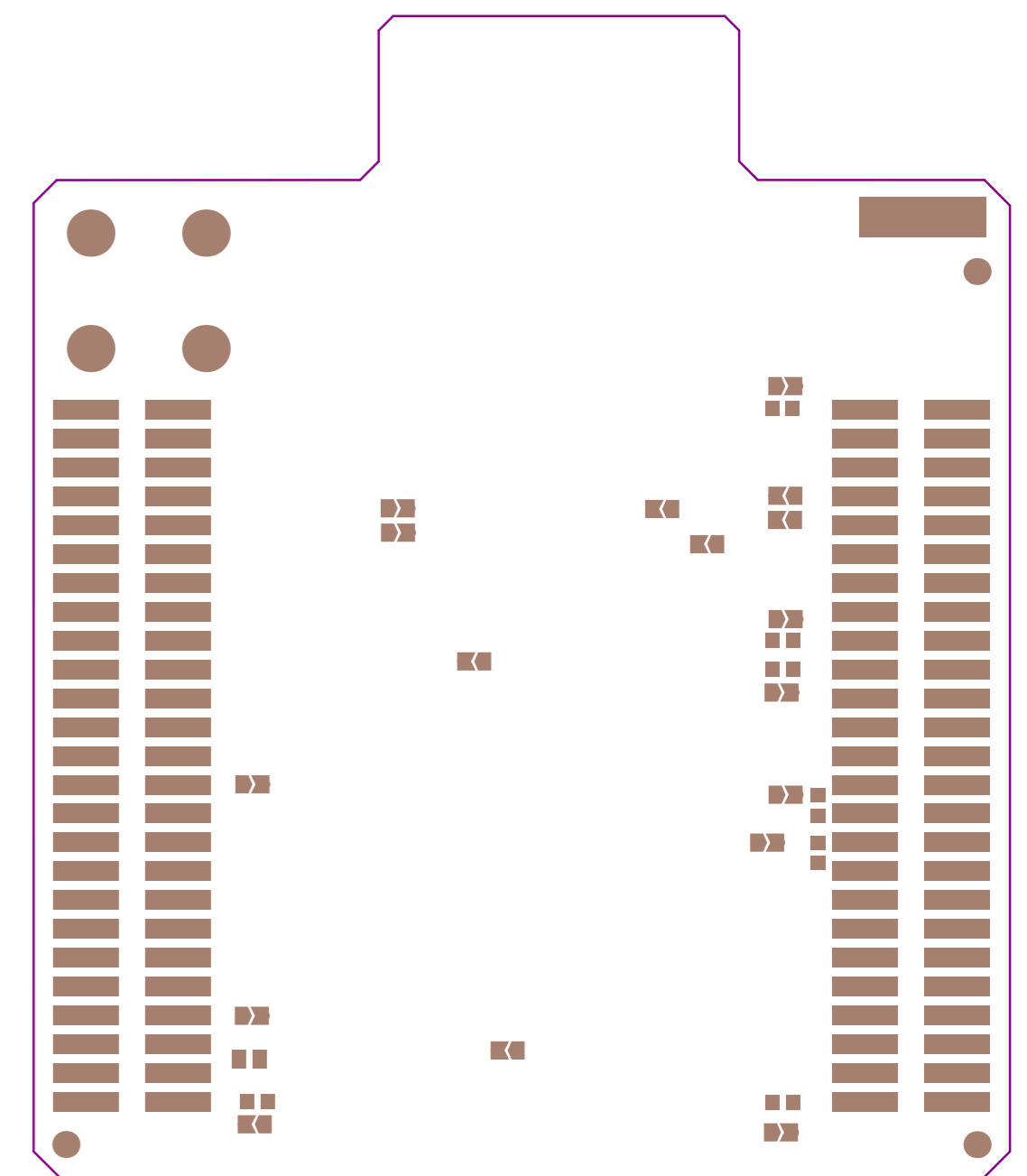


Project: MCU RF Board Bluefish 2M QFN68		
Layer: Signal Layer 2	Gerber: .G2	
Variant: [No Variations]	Ref: MB2130	
Date: 23-FEB-24	Rev: A	



Project: MCU RF Board Bluefish 2M QFN68	
Layer: Bottom Layer	Gerber: .GBL
Variant: [No Variations]	Ref: MB2130
Date: 23-FEB-24	Rev: A





Project: MCU RF Board Bluefish 2M QFN68

Layer: Bottom Solder

Gerber: .GBS

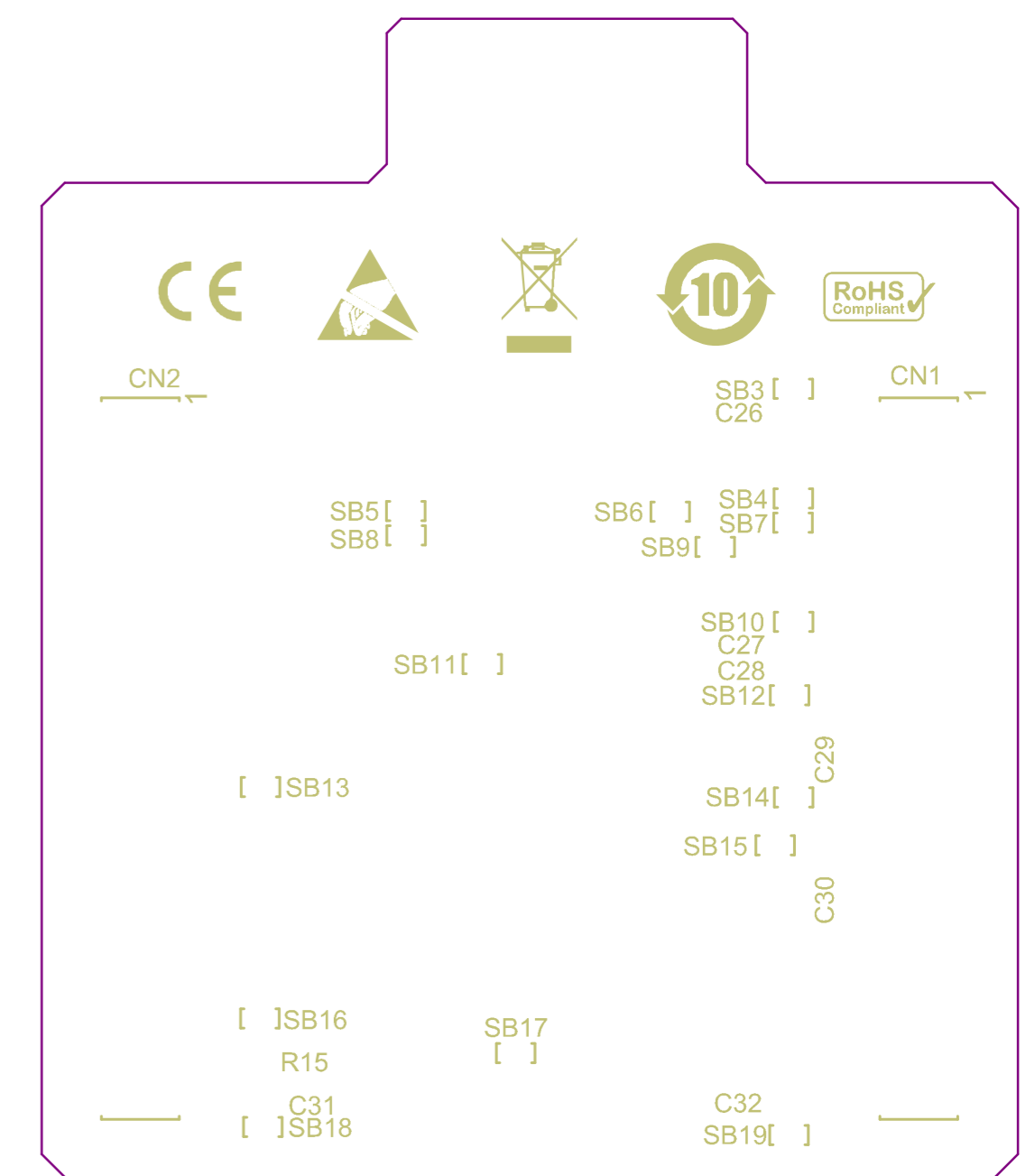
Variant: [No Variations]


Ref: MB2130

Date: 23-FEB-24

Rev: A





Project: MCU RF Board Bluefish 2M QFN68		
Layer: Bottom Overlay	Gerber: .GBO	
Variant: [No Variations]	Ref: MB2130	
Date: 23-FEB-24	Rev: A	

PCB SPECIFICATIONS :

A. MATERIAL :

FR-4

☐ TG-170

☒ TG-150

☐ TG-140

B. MATERIAL FAMILY :

N/A

C. SOLDERMASK COLOR :

☐ GREEN

☒ BLUE

☐ RED

☐ BLACK

D. SILKSCREEN COLOR :

☒ WHITE

☐ YELLOW

☐ BLACK

E. SURFACE FINISH :

☒ ENIG

☐ IMMERSION SILVER

☐ IMMERSION TIN

☐ HASL

☐ HASL (PB-FREE)

☐ GOLDEN FINGER

☒ IMPEDANCE CONTROL :

☒ NO

☐ YES (SEE IMPEDANCE TABLE FOR DETAIL INFORMATION)

G. THROUGH VIA :

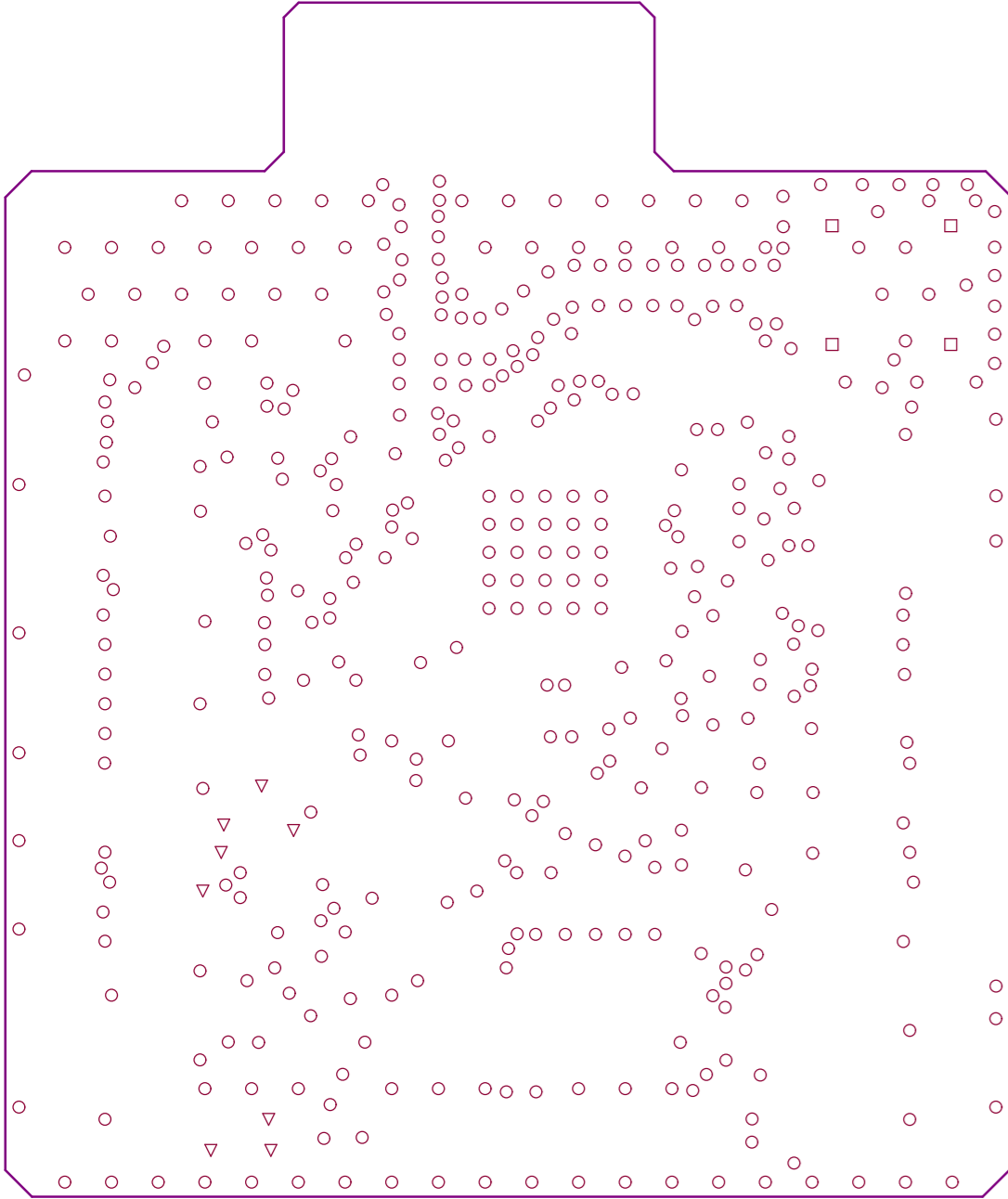
PLUG THE VIAS WHICH ARE COVERED WITH SOLDERMASK ONE OR TWO SIDE.

PLUG MATERIAL : ☒ SOLDERMASK

☐ NON-CONDUCTIVE EPOXY.

☒ STACK-UP :

SEE LAYER STACK-UP SEQUENCE FOR OVERALL THICKNESS.



Layer	Name	Material	Thickness	Constant	Board Layer Stack
	Top Overlay				/ / / / / / / / / /
	Top Solder	Solder Resist	0.79mil	3.5	
1	Top Layer		2.76mil		/ / / / / / / / / /
	Dielectric 1	1080HR RC68	2.99mil	4.2	
2	Signal Layer 1		1.38mil		/ / / / / / / / / /
	Dielectric 2	FR4	48.43mil	4.5	
3	Signal Layer 2		1.38mil		/ / / / / / / / / /
	Dielectric 3	1080HR RC68	2.99mil	4.2	
4	Bottom Layer		2.76mil		/ / / / / / / / / /
	Bottom Solder	Solder Resist	0.79mil	3.5	
	Bottom Overlay				/ / / / / / / / / /

Symbol	Count	Hole Size	Plated	Hole Type	Drill Layer Pair	Via/Pad	Pad Shape	Template	Description
▽	8	11.81mil (0.30mm)	PTH	Round	Top Layer - Bottom Layer	Via	Rounded	v55h30m0mx0	
○	425	13.78mil (0.35mm)	PTH	Round	Top Layer - Bottom Layer	Via	Rounded	v55h35m0mx0	
□	4	43.31mil (1.10mm)	PTH	Round	Top Layer - Bottom Layer	Pad	Rounded	c200h110m205	
	437 Total								

Project: MCU RF Board Bluefish 2M QFN68	
Layer: Drill Drawing	Gerber: .DRL
Variant: [No Variations]	Ref: MB2130
Date: 23-FEB-24	Rev: A

